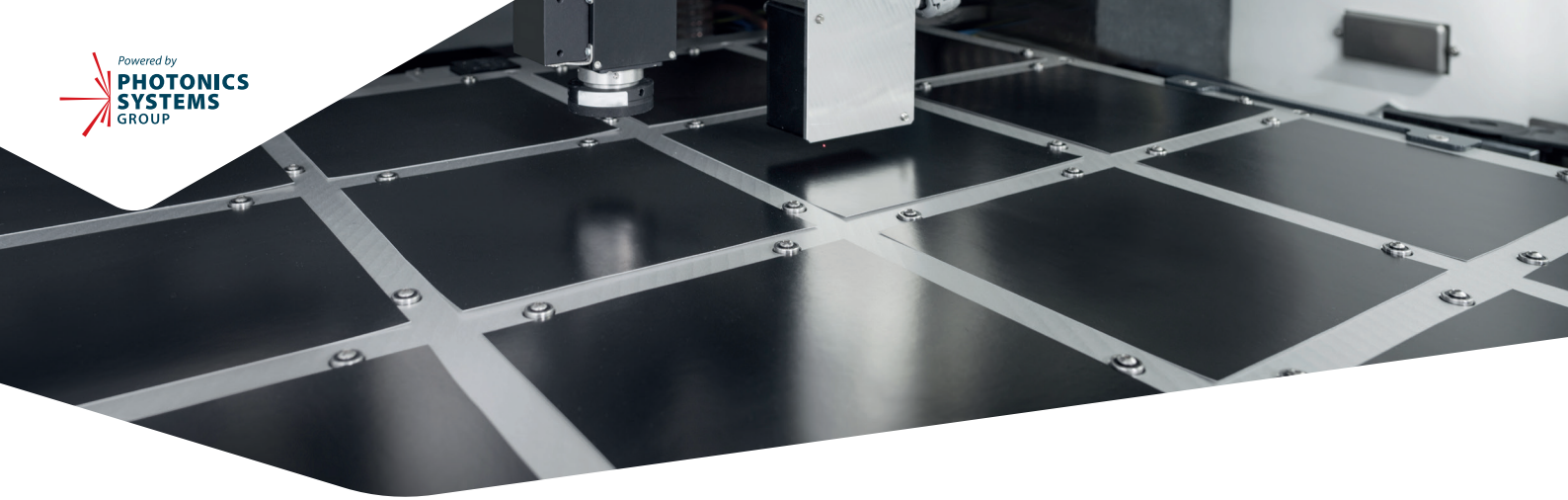


High Precision Laser Machine for Large Substrates



ELEKTRONIC

EXPEGO



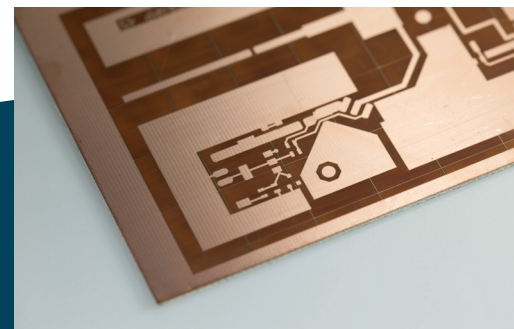
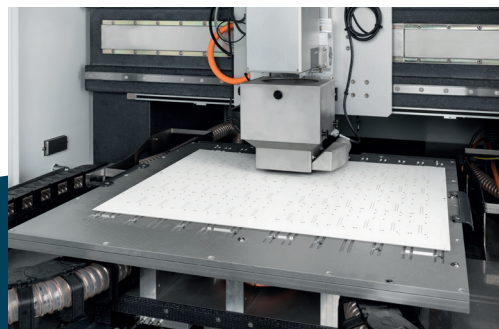
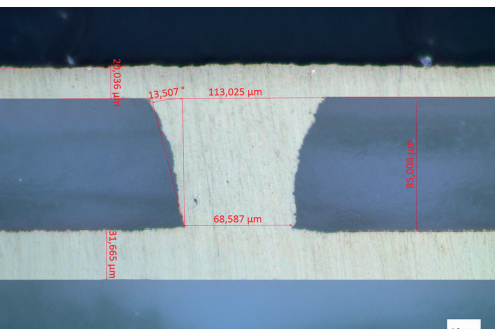
EXPEGO

Benefits

- ◆ Processing multiple substrates in parallel
- ◆ Very flexible design with highest degree of customization for various applications
- ◆ Flexible chuck design
- ◆ High precise and ultrafast laser system
- ◆ Industry 4.0 ready
- ◆ Automatic camera calibration
- ◆ Automated routines for reference runs
- ◆ Automated vision system for precision alignment and scaling, offset, trapezoidal and rotation compensation

Options

- ◆ Up to 3 lasers sources with beam switches
- ◆ InnoLas Postprocessor for CAD file transfer
- ◆ Exhaust system
- ◆ MES Interface
- ◆ Auto focus
- ◆ Integrated process metrology
- ◆ INFINITY Scan to avoid stitching errors while increasing process speed (simultaneous axis and scanner movement)



Technical Data

Optic	Fixed optic or High Speed Scanner setup
Axis	X-Y / Z
Accuracy	< ± 5 µm abs. (± 0.197 Mils)
Repeatability	< ± 2 µm (± 0.079 Mils)
Substrate Size	Up to 29.5" x 29.5" (750 mm x 750 mm)
Material	Rigid-, flex-PCBs, ceramic, glass and advanced materials
Image System	InnoLas µVision
Software	Windows 10; IoT
Platform type	Granite based

Automation

- ◆ Fully and semi-automatic InnoLas Automation
- ◆ Customized automation solutions
- ◆ Stand Alone System
- ◆ SMEMA compatible with 3rd party automation

Laser processes

- ◆ Laser Drilling
- ◆ Laser Depaneling
- ◆ Laser Scribing
- ◆ Laser Ablation